

# Low Voltage Quad 2-Input AND Gate

# **74LVX08**

#### **Description**

The LVX08 contains four 2-input AND gates. The inputs tolerate voltages up to 6.5 V allowing the interface of 5 V systems to 3 V systems.

#### **Features**

- Input Voltage Level Translation from 5 V to 3 V
- Ideal for Low Power/Low Noise 3.3 V Applications
- Guaranteed Simultaneous Switching Noise Level and Dynamic Threshold Performance

# **ABSOLUTE MAXIMUM RATINGS**

Symbol	Para	Ratings	Unit	
V <sub>CC</sub>	Supply Voltage		-0.5 to 6.5	V
I <sub>IK</sub>	DC Input Diode Cu	ırrent, V <sub>I</sub> = −0.5 V	-20	mA
VI	DC Input Voltage		-0.5 to 6.5	V
I <sub>OK</sub>	DC Output Diode V <sub>O</sub> = -0.5 V		-20	mA
	Current	Current $V_O = V_{CC} + 0.5 \text{ V}$		
Vo	DC Output Voltage	-0.5 to V <sub>CC</sub> + 0.5	V	
I <sub>O</sub>	DC Output Source	or Sink Current	±25	mA
I <sub>CC</sub> or I <sub>GND</sub>	DC V <sub>CC</sub> or Ground	l Current	±50	mA
T <sub>STG</sub>	Storage Temperatu	ure	-65 to 150	°C
P <sub>D</sub>	Power	SOIC	1077	mW
	Dissipation		833	
TL	Lead Temperature (Soldering, 10 Sec	240	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### **RECOMMENDED OPERATING CONDITIONS** (Note 1)

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	Supply Voltage	2.0	3.6	V
VI	Input Voltage	0	5.5	V
Vo	Output Voltage	0	$V_{CC}$	V
T <sub>A</sub>	Operating Temperature	-40	+85	°C
$\Delta t / \Delta V$	Input Rise and Fall Time	0	100	ns/V

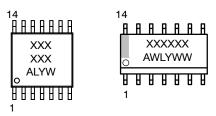
Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

1. Unused inputs must be held HIGH or LOW. They may not float.





#### MARKING DIAGRAM



XXX = Specific Device Code
A = Assembly Location

WL, L = Wafer Lot Y = Year WW, W = Work Week

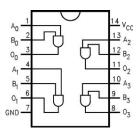


Figure 1. Connection Diagram

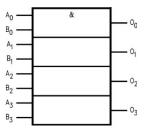


Figure 2. Logic Symbol

#### **PIN DESCRIPTION**

PIN NAMES	DESCRIPTION
A <sub>n</sub> , B <sub>n</sub>	Inputs
O <sub>n</sub>	Outputs

# **ORDERING INFORMATION**

See detailed ordering and shipping information on page 3 of this data sheet.

# 74LVX08

# DC ELECTRICAL CHARACTERISTICS

					T <sub>A</sub> = 25°(	)	T <sub>A</sub> = -	-40°C to	+85°C	
Symbol	Parameter	V <sub>CC</sub>	Conditions	Min	Тур	Max	Min	Тур	Max	Unit
V <sub>IH</sub>	HIGH Level Input	2.0		1.5	-	-	1.5	-	-	V
	Voltage	3.0		2.0	-	-	2.0	-	-	
		3.6		2.4	-	-	2.4	-	-	
V <sub>IL</sub>	LOW Level Input	2.0		-	-	0.5	-	-	0.5	V
	Voltage	3.0		-	-	0.8	-	-	0.8	
		3.6		-	-	0.8	-	-	0.8	
V <sub>OH</sub>	HIGH Level Output Voltage	2.0	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -50 \mu A$	1.9	2.0	-	1.9	_	-	V
		3.0	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -50 \mu A$	2.9	3.0	-	2.9	-	-	
			$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -4 \text{ mA}$	2.58	_	_	2.48	-	-	
V <sub>OL</sub>	LOW Level Output Voltage	2.0	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = -50  \mu\text{A}$	-	0.0	0.1	-	-	0.1	V
		3.0	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = -50  \mu\text{A}$	-	0.0	0.1	-	_	0.1	
			$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = -4 \text{ mA}$	-	-	0.36	-	_	0.44	
I <sub>IN</sub>	Input Leakage Current	3.6	V <sub>IN</sub> = 5.5 V or GND	-	-	±0.1	-	-	±1.0	μΑ
Icc	Quiescent Supply Current	3.6	V <sub>IN</sub> = V <sub>CC</sub> or GND	-	-	2.0	-	-	20.0	μΑ

# NOISE CHARACTERISTICS (Note 2)

				T <sub>A</sub> = −40°C		
Symbol	Parameter	V <sub>CC</sub> (V)	C <sub>L</sub> (pF)	Тур	Limit	Unit
V <sub>OLP</sub>	Quiet Output Maximum Dynamic V <sub>OL</sub>	3.3	50	0.3	0.8	V
V <sub>OLV</sub>	Quiet Output Minimum Dynamic V <sub>OL</sub>	3.3	50	-0.3	-0.5	V
V <sub>IHD</sub>	Minimum HIGH Level Dynamic Input Voltage	3.3	50	-	2.0	V
$V_{ILD}$	Maximum LOW Level Dynamic Input Voltage	3.3	50	-	0.8	V

<sup>2.</sup> Input  $t_r = t_f = 3 \text{ ns}$ 

# **AC ELECTRICAL CHARACTERISTICS**

				T <sub>A</sub> = 25°C		T <sub>A</sub> = -40°C to +85°C				
Symbol	Parameter	V <sub>CC</sub>	Conditions	Min	Тур	Max	Min	Тур	Max	Unit
t <sub>PLH</sub> , t <sub>PHL</sub> Propagation Delay	2.7	C <sub>L</sub> = 15 pF	-	6.3	11.4	1.0	-	13.5	ns	
	Time		C <sub>L</sub> = 50 pF	-	8.8	14.9	1.0	-	17.0	
		3.3 ± 0.3	C <sub>L</sub> = 15 pF	-	4.8	7.1	1.0	-	8.5	
			C <sub>L</sub> = 50 pF	-	7.3	10.6	1.0	-	12.0	
toslh, toshl Output to Output	2.7	C <sub>L</sub> = 50 pF	-	-	1.5	-	-	1.5	ns	
	Skew (Note 3)	3.3		-	-	1.5	-	_	1.5	

<sup>3.</sup> Parameter guaranteed by design t<sub>OSLH</sub> = |t<sub>PLHm</sub> - t<sub>PLHn</sub>|, t<sub>OSHL</sub> = |t<sub>PHLm</sub> - t<sub>PHLn</sub>|.

#### 74LVX08

# **CAPACITANCE**

		T <sub>A</sub> = 25°C		T <sub>A</sub> = -40°C to +85°C				
Symbol	Parameter	Min	Тур	Max	Min	Тур	Max	Unit
C <sub>IN</sub>	Input Capacitance	_	4	10	-	_	10	pF
C <sub>PD</sub>	Power Dissipation Capacitance (Note 4)	_	18	-	-	-	-	pF

<sup>4.</sup>  $C_{PD}$  is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation:  $I_{CC(opr.)} = \frac{C_{PD} \times V_{CC} \times f_{IN} \times I_{CC}}{4 \ (per \ Gate)}$ 

# **ORDERING INFORMATION**

Product Number	Package	Marking	Shipping <sup>†</sup>
74LVX08MTCX	TSSOP-14 WB (Pb-Free/Halide Free)	LVX 08	2500 / Tape and Reel
74LVX08MX	SOIC14 (Pb-Free/Halide Free)	LVX08	2500 / Tape and Reel

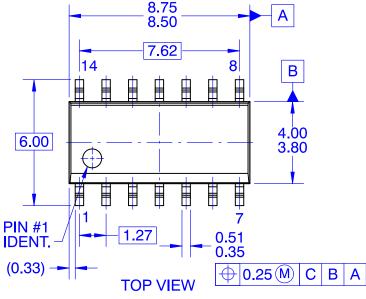
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

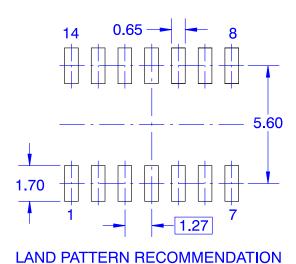
<sup>\*-</sup>Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

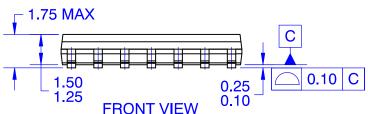


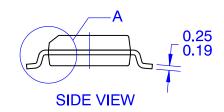
SOIC14 CASE 751EF **ISSUE O** 

**DATE 30 SEP 2016** 



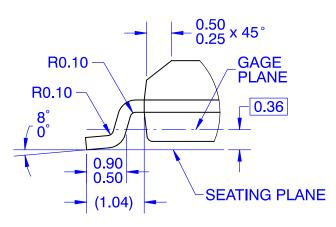






# NOTES:

- A. CONFORMS TO JEDEC MS-012, VARIATION AB, ISSUE C
  B. ALL DIMENSIONS ARE IN MILLIMETERS
- C. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS
- D. LAND PATTERN STANDARD:
- SOIC127P600X145-14M
- E. CONFORMS TO ASME Y14.5M, 2009



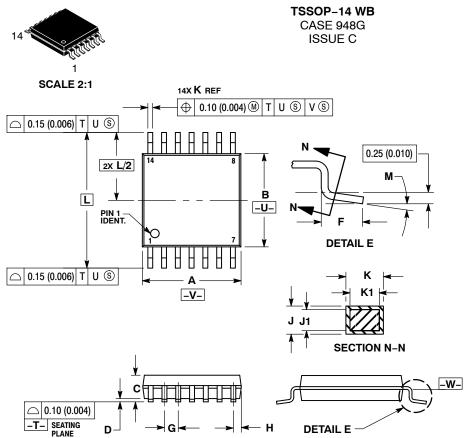
**DETAIL A SCALE 16:1** 

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- NOTES.

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: MILLIMETER.

  3. DIMENSION A DOES NOT INCLUDE MOLD
- FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  DIMENSION B DOES NOT INCLUDE
- INTERLEAD FLASH OR PROTRUSION.
  INTERLEAD FLASH OR PROTRUSION SHALL
- INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

  5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.

  6. TERMINAL NUMBERS ARE SHOWN FOR DEFERENCE ONLY
- REFERENCE ONLY.
  DIMENSION A AND B ARE TO BE
- DETERMINED AT DATUM PLANE -W-

	MILLIMETERS		INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	4.90	5.10	0.193	0.200	
В	4.30	4.50	0.169	0.177	
С		1.20		0.047	
D	0.05	0.15	0.002	0.006	
F	0.50	0.75	0.020	0.030	
G	0.65	BSC	0.026 BSC		
Н	0.50	0.60	0.020	0.024	
J	0.09	0.20	0.004	0.008	
J1	0.09	0.16	0.004	0.006	
K	0.19	0.30	0.007	0.012	
K1	0.19	0.25	0.007	0.010	
L	6.40		0.252 BSC		
М	0 °	8 °	0 °	8 °	

#### **GENERIC MARKING DIAGRAM\***



= Assembly Location

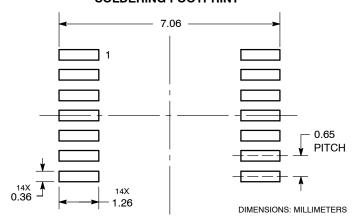
= Wafer Lot L = Year = Work Week W

= Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

#### **RECOMMENDED SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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